

TAZMO

Financial Announcement

Q3 FY2024

November 11, 2024

Security Code 6266

Company Guide



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Q3 FY2024 Consolidated Financial Summary

Net sales

24,739

million Yen

Operating income

4,601

million Yen

Ordinary income

4,524

million Yen

Net income(*)

3,094

million Yen

■ Overview

- Although net sales fell short of the plan by approximately 1.5 billion yen due to delays in equipment delivery and startup schedules, they increased by 30% year-over-year.
- Profit exceeded the plan significantly, increasing by 68.2% year-over-year, driven by the rise in net sales and by reductions in R&D expenses, depreciation costs, and SG&A expenses, which were lower than anticipated.
- While market recovery has been slow, there is a growing trend of increased inquiries in advanced packaging and power devices.

(*) Net income: Net income attributable to owners of parent

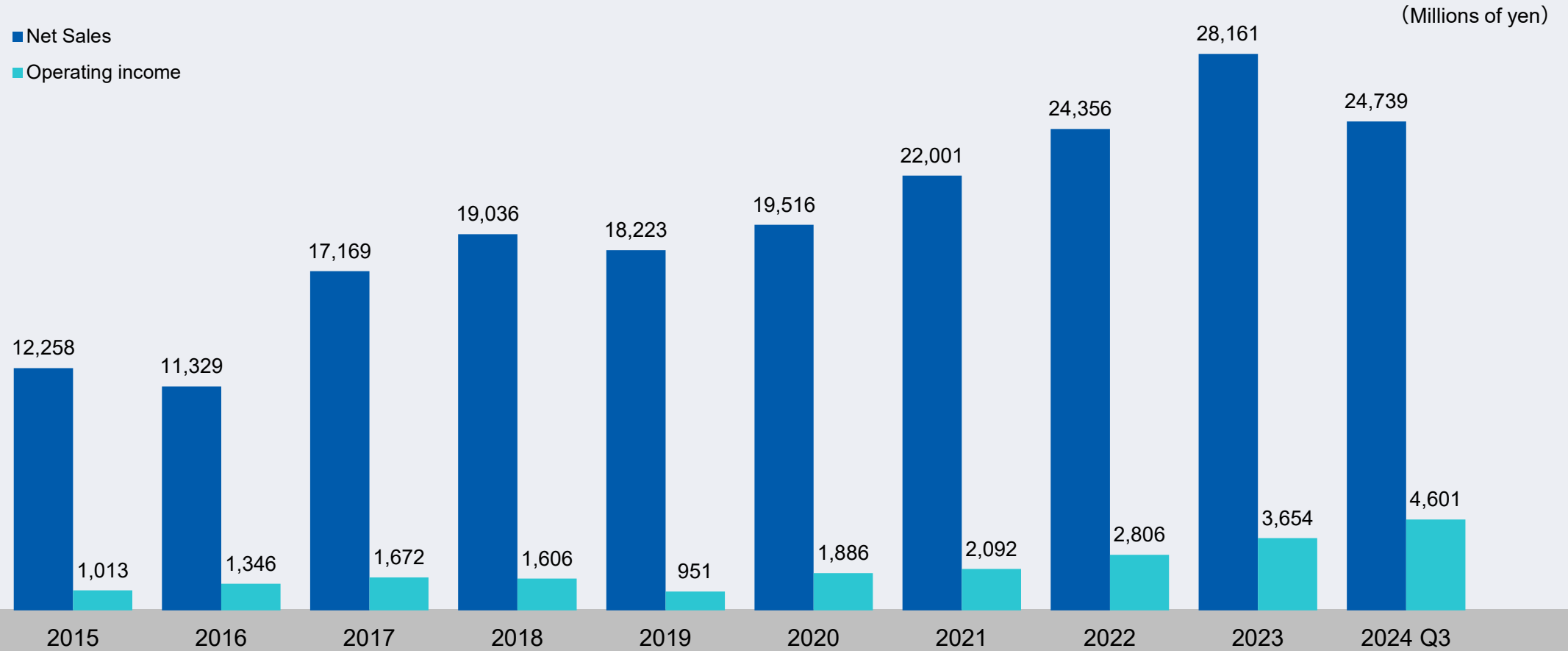
Financial Summary

(Millions of yen)	Q3 FY2023 (Actual)	Q3 FY2024		YoY change (%)	FY2024 estimates	cf. Plan
		Actual	Net sales ratio (%)			
Net sales	19,034	24,739	—	30.0	36,000	68.7
Gross profit	5,944	8,661	35.0	45.7	—	—
Operating income	2,405	4,601	18.6	91.3	4,600	100.0
Ordinary income	2,690	4,524	18.3	68.2	4,500	100.5
Net income attributable to owners of parent	1,539	3,094	12.5	101.1	3,060	101.1

Trend in Net sales and Operating profit (Quarterly)



Trend in Net sales and Operating profit (Full year)



(Millions of yen)	FY2023	Q3 FY2024	YoY change(%)
Current assets	39,420	40,053	1.6
Non-current assets	8,008	8,012	0.0
Property, plant and equipment	7,007	7,001	0.0
Intangible assets	157	145	△7.6
Investments and other assets	842	865	2.7
Total assets	47,428	48,065	1.3
Current Liabilities	21,380	17,654	△17.5
Non-Current Liabilities	5,952	7,405	24.4
Total liabilities	27,333	25,060	△8.3
Total net assets	20,095	23,005	14.5
Equity ratio	41.7%	47.1%	5.4P

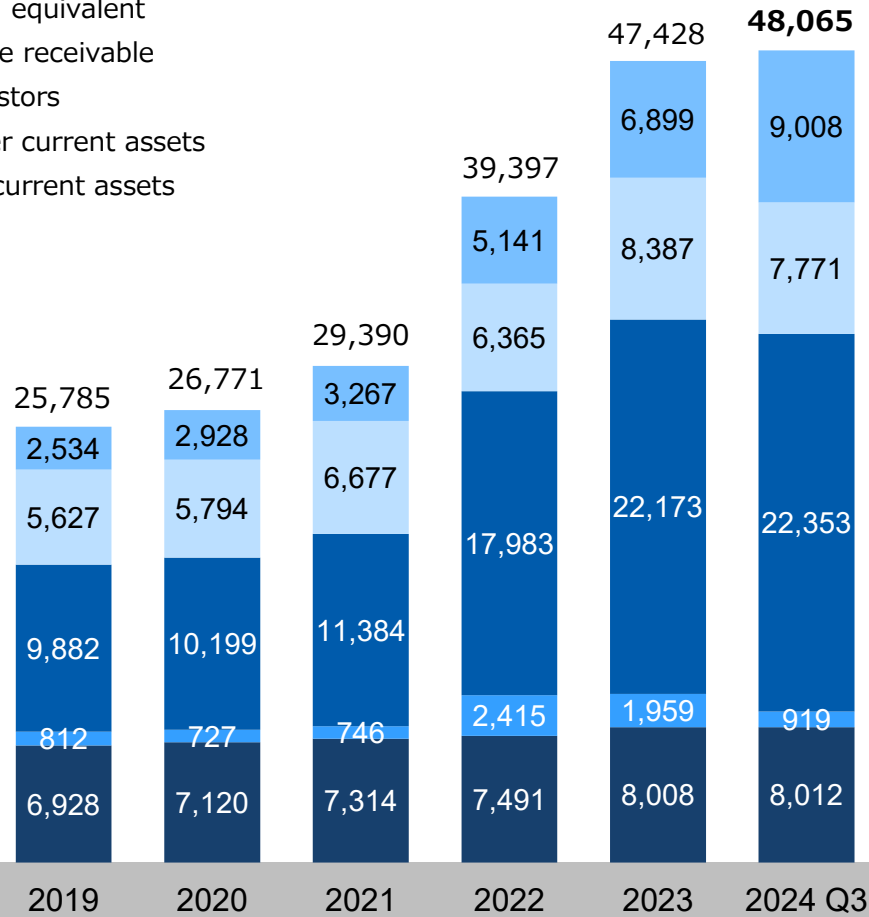
Major Change

Current Assets	(Millions of yen)
Cash and deposits	+2,108
Notes and accounts receivable - trade	△1,405
Current Liabilities	
Short-term borrowings	△3,710
Non-Current Liabilities	
Long-term borrowings	+1,448

Assets

(Millions of yen)

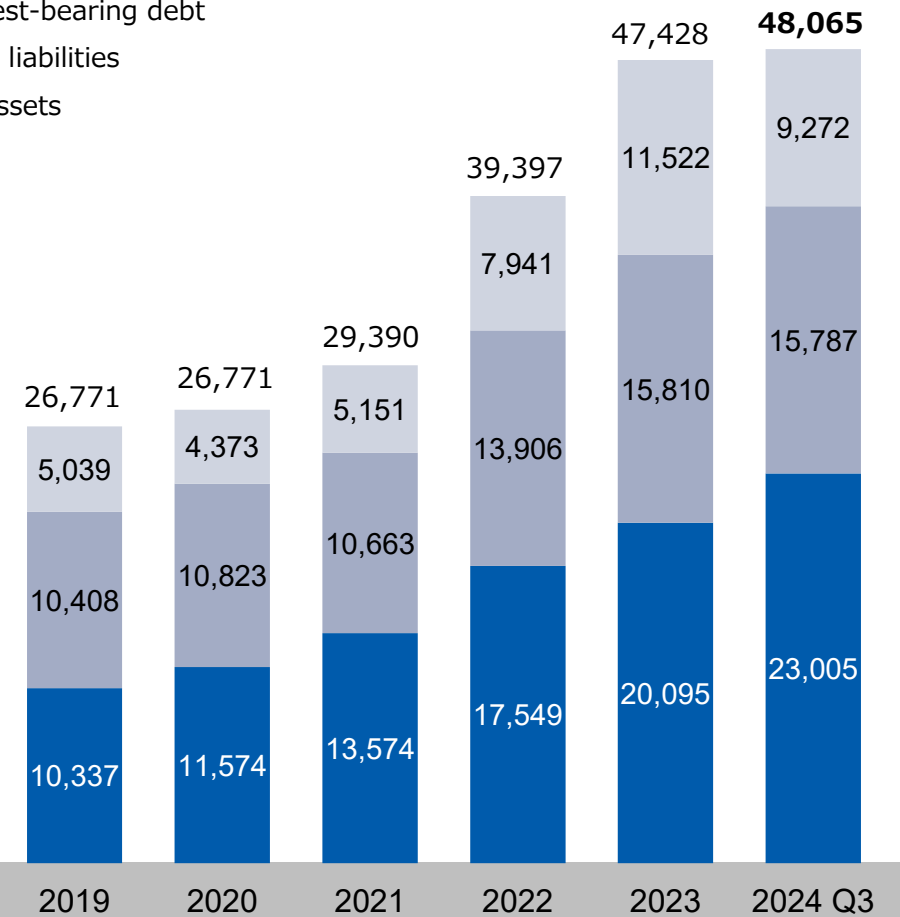
- Cash equivalent
- Trade receivable
- Investors
- Other current assets
- Noncurrent assets



Liabilities/Equity

(Millions of yen)

- Interest-bearing debt
- Other liabilities
- Net assets





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Q3 FY2024 Segment Information

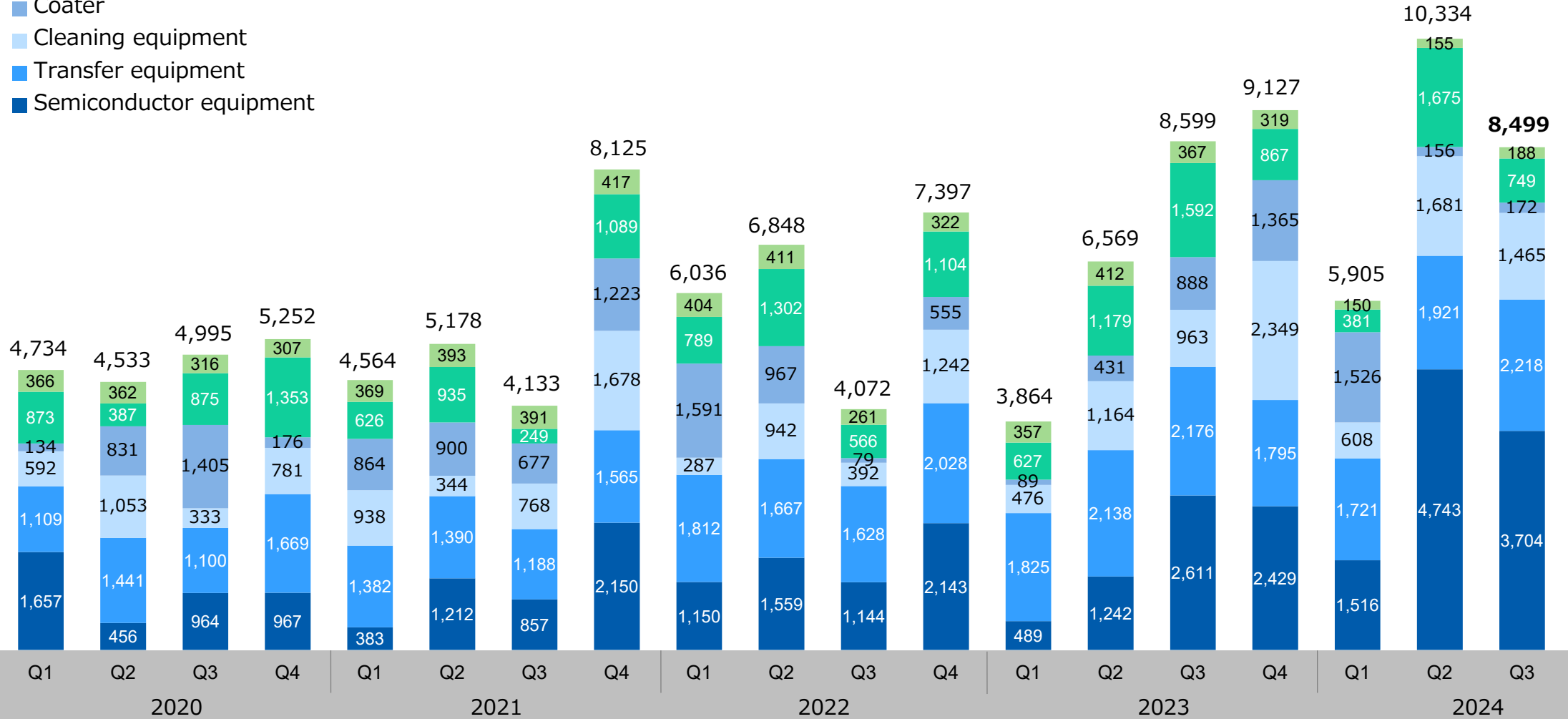
Net Sales and Operating Profit by Segment

		Q3 FY2023 Actual	Q3 FY2024 Actual	YoY change(%)	FY2024 Initial estimates	cf. Plan (%)
(Millions of yen)						
Process equipment business	Net sales	14,497	21,438	47.9	27,770	77.2
	Operating income	2,333	4,491	92.5	4,250	105.7
■ Semiconductor equipment	Net sales	4,343	9,964	129.4	11,500	86.6
■ Transfer equipment	Net sales	6,140	5,862	△4.5	8,100	72.4
■ Cleaning equipment	Net sales	2,604	3,756	44.2	5,800	64.8
■ Coater	Net sales	1,408	1,855	31.7	2,370	78.3
Precision molding dies and plastic moldings business	Net sales	1,137	494	△56.6	1,700	29.1
	Operating income	19	△217	—	30	—
Surface treatment equipment business	Net sales	3,399	2,805	△17.5	6,530	43.0
	Operating income	69	322	366.7	320	100.6
Elimination of inter-segment transactions	Operating income	△17	5	—	—	—
Total	Net sales	19,034	24,739	30.0	36,000	68.7
	Operating income	2,405	4,601	91.3	4,600	100.0

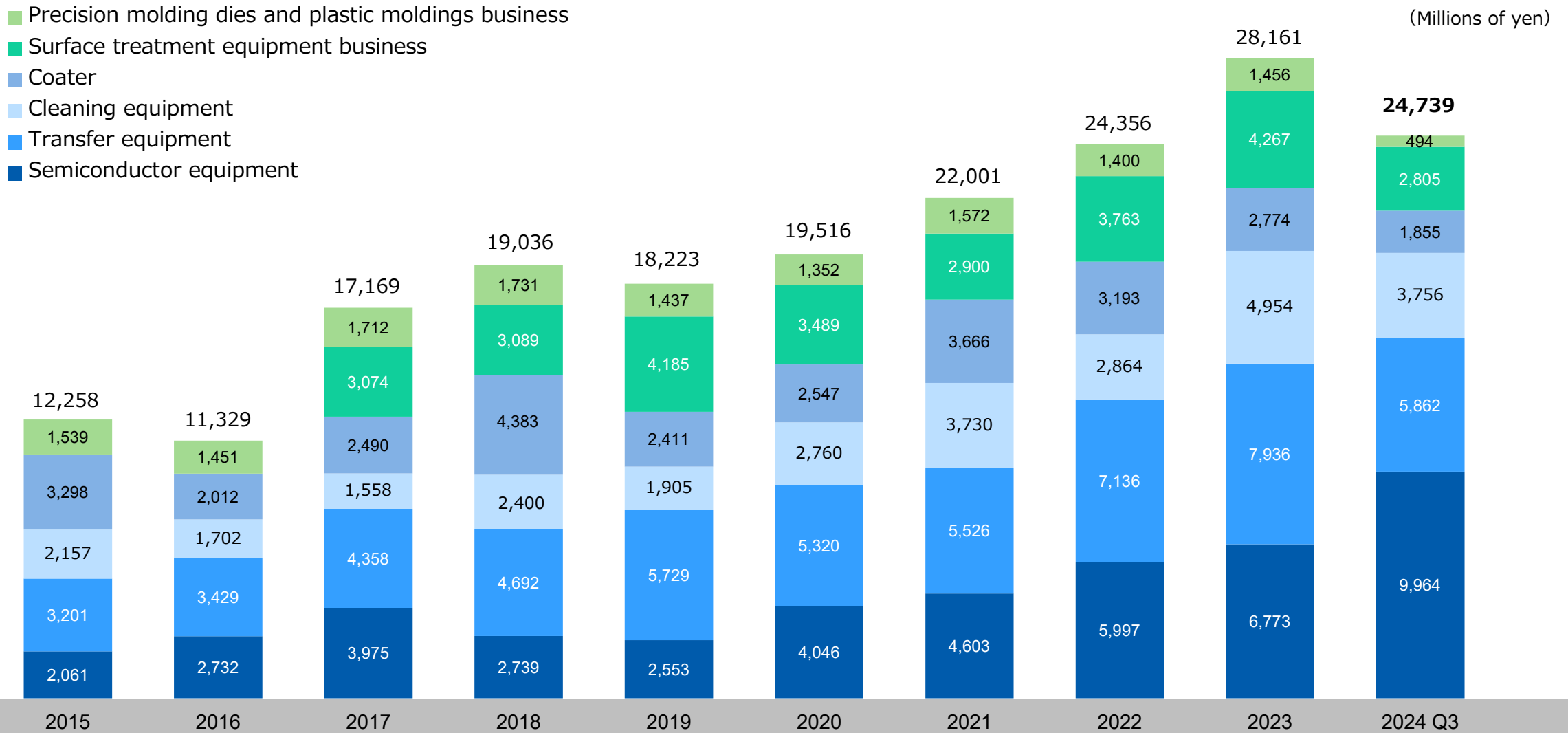
Trend in Net sales by Segment (Quarterly)

(Millions of yen)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment



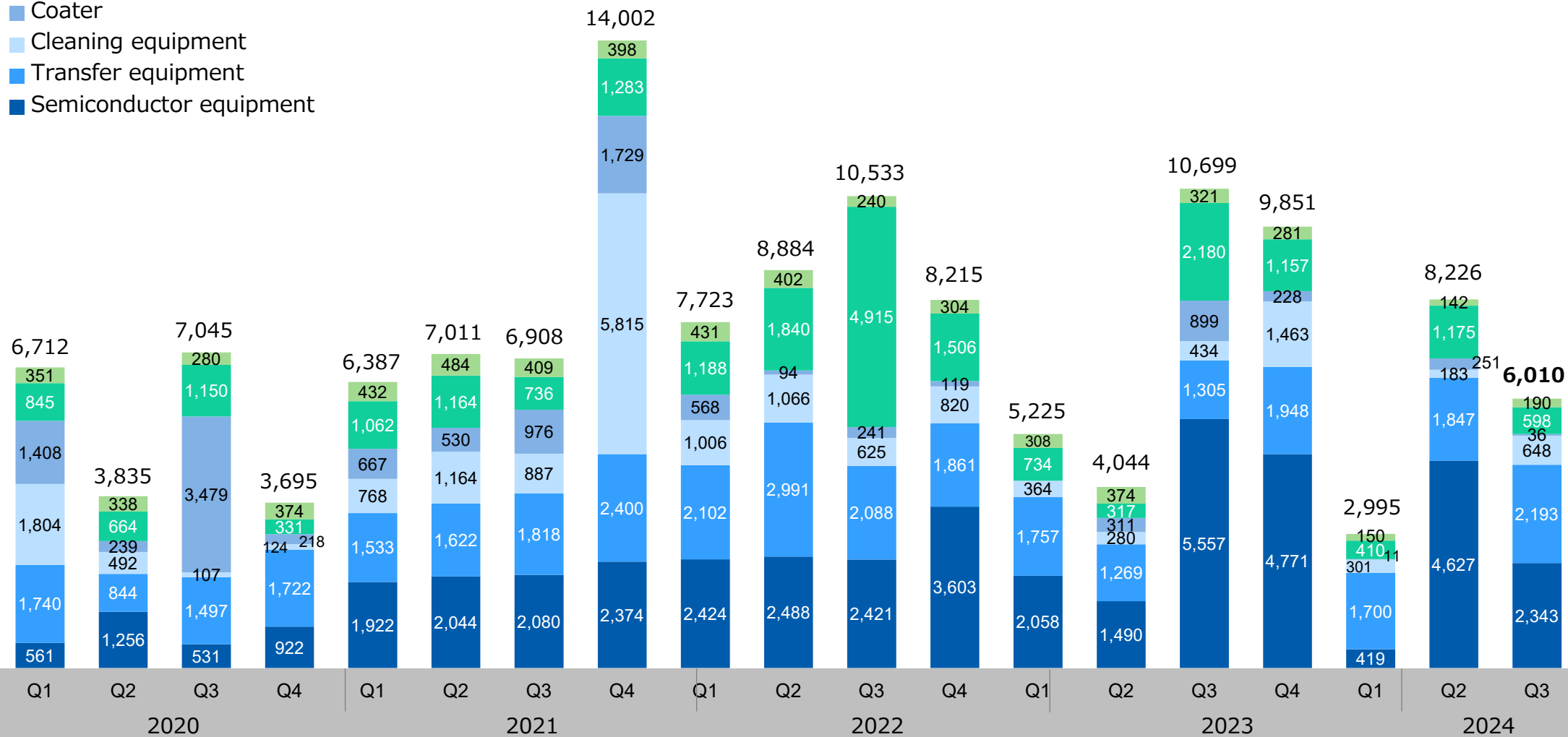
Trend in Net sales by Segment (Full year)



Trend in Sales Orders by Segment (Quarterly)

(Millions of yen)

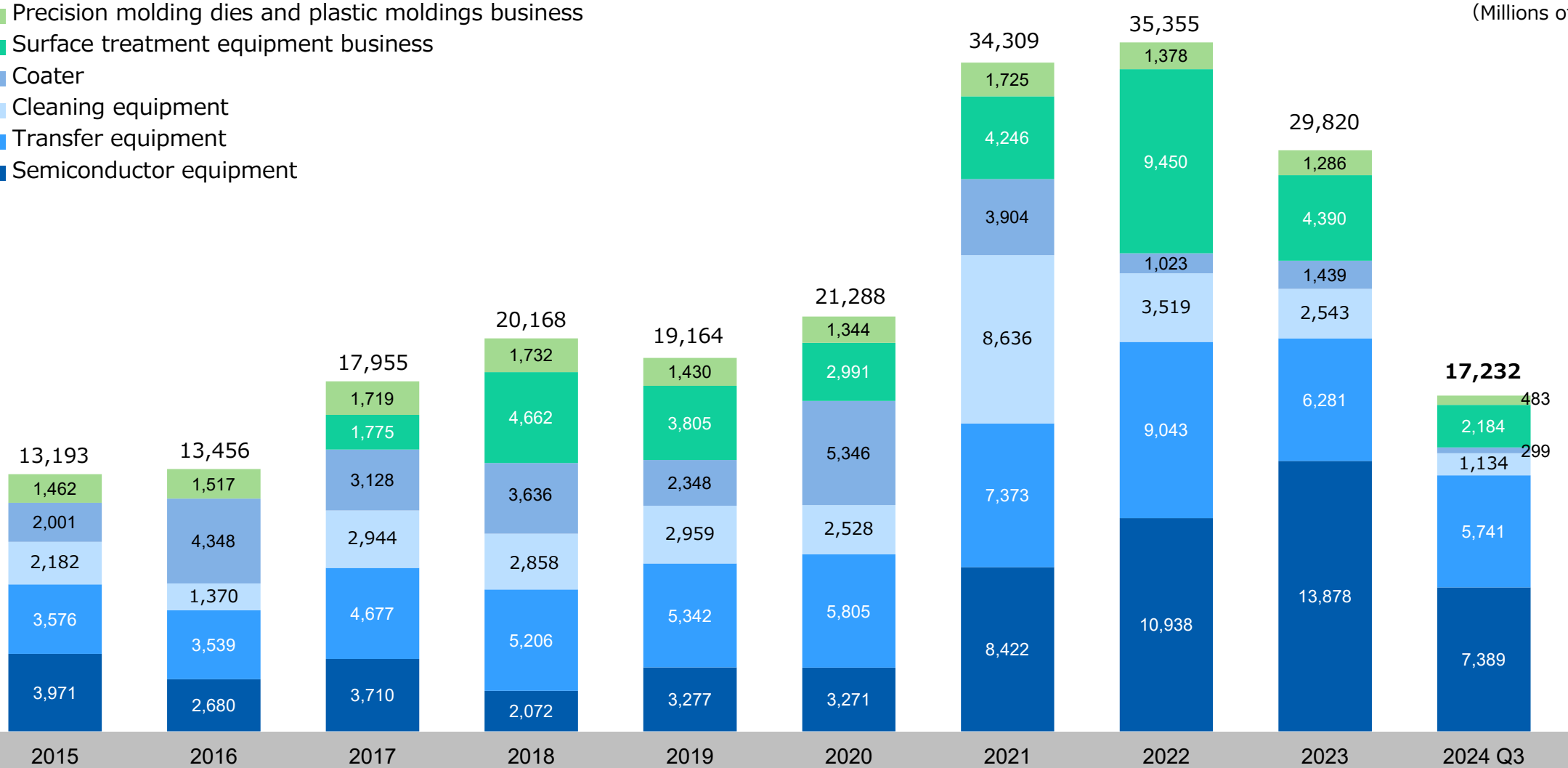
- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment



Trend in Sales Orders by Segment (Full year)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment

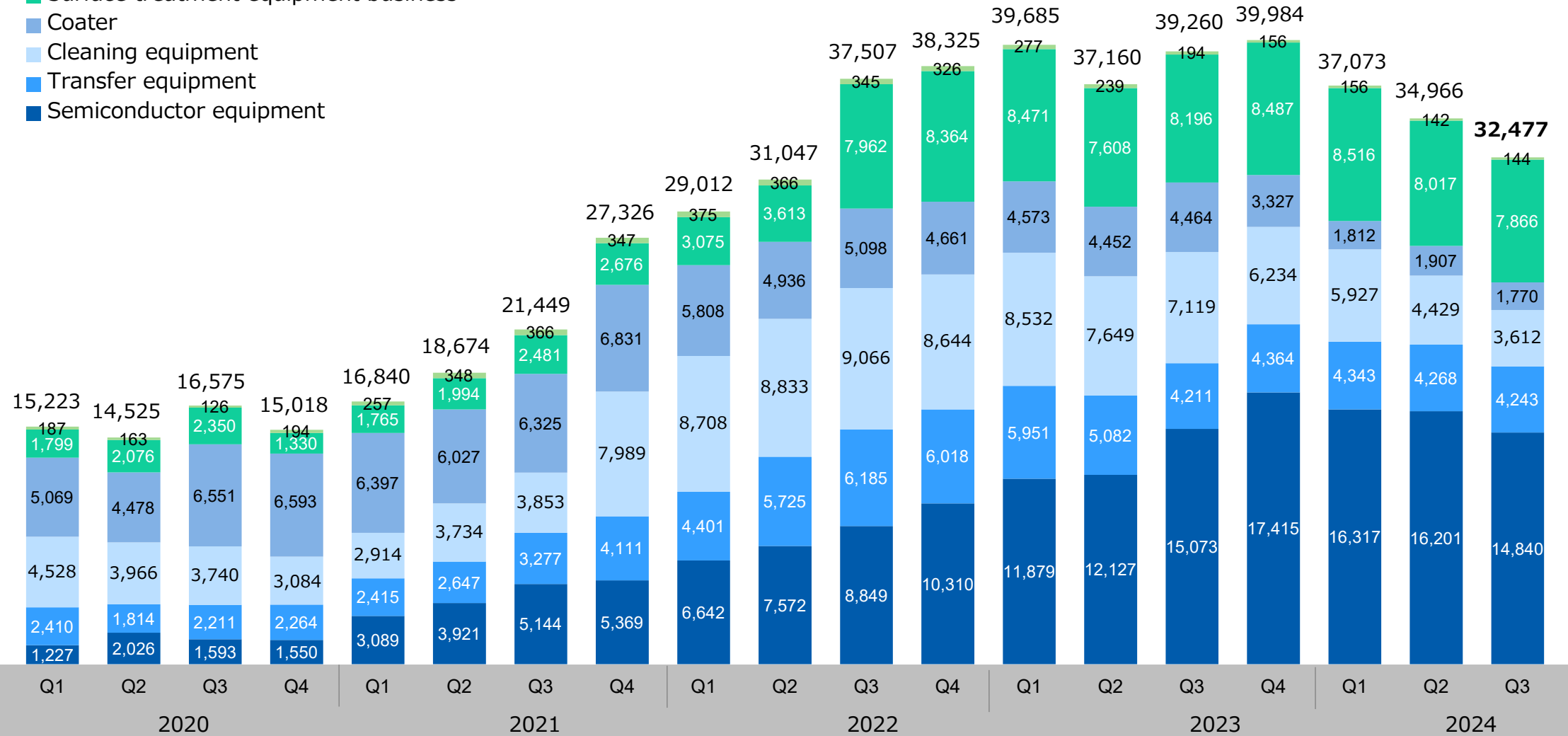
(Millions of yen)



Trend in Order Backlog by Segment (Quarterly)

(Millions of yen)

- Precision molding dies and plastic moldings business
- Surface treatment equipment business
- Coater
- Cleaning equipment
- Transfer equipment
- Semiconductor equipment





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Business Environment

- In semiconductor manufacturing equipment, we received a substantial order for advanced packaging equipment, with continued orders expected. We anticipate further market expansion. Although some shipments for power semiconductor equipment have been delayed, inquiries are gradually increasing. We are preparing for a recovery in investment.
- For transport equipment, it may take a bit more time for inquiries to recover fully. However, the number of projects, including frame-related projects we are focusing on, is increasing, leading to higher order volumes.
- Inquiries for slurry supply systems are progressing steadily, and orders remain strong. We are also beginning to see new project discussions for cleaning equipment, and we are actively working to secure orders.
- Inquiries for PLP equipment are increasing, primarily for R&D and mass production. We are focusing on sales, development, and process evaluation to secure each order steadily, with expectations for future market growth.
- For surface treatment equipment, the number of projects involving wet processing equipment, including plating, is declining compared to previous levels. We are working to expand orders by focusing on new development and inquiries in both wet processing and substrate transport equipment.



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Appendix

Company name	TAZMO Co., Ltd.	
Established	February 26, 1972	
Head office	5311, Haga, Kita-ku, Okayama-shi, Okayama 701-1221, Japan	
Capital	356,859,682 yen	
Total number of issued shares	14,842,354	
Number of shareholders	8,148	(as of June 30, 2024)
Number of employees	Non-consolidated 394 Consolidated 1,172	(as of September 30, 2024)
Business content	Development, Manufacturing and Sales of Semiconductor Manufacturing Equipment, Clean Transfer System, LCD Manufacturing Equipment, UV Laser Equipment, Plating Equipment, Mold・Resin Molding, Plating/Circuit formation Equipment for PCB	

Domestic locations, Subsidiaries

- Okayama-shi, Okayama**
Head office
- Izumo-shi, Shimane**
Facility Ci., Ltd. Izumo Laboratory
- Ibara-shi, Okayama**
TAZMO Plant No.1
TAZMO Plant No.3
TAZMO Plant No.5
Quark Technology Co., Ltd.
PRETEC Co., Ltd.
- Shinjuku-ku, Tokyo**
Tokyo office
- Yokohama-shi, Kanagawa**
Quark Technology Co., Ltd.
Yokohama office
- Sagamihara, Kanagawa**
Facility Co., Ltd.

Global Network

- Doungguan City, Guangdong Province, China**
Facility Technology (Dongguan) Co., Ltd.
- Hong Kong**
Facility (HK) Co., Ltd.
- Shanghai**
TAZMO Apprecia Electronics Inc.
Shanghai TAZMO Precision Machinery Co., Ltd.
- Shaoxing City, Zhejiang Province, China**
TAZMO Semitec Shaoxing Technology Co., Ltd.
- Taiwan**
TAZMO Apprecia Formosa Inc.
- San Francisco**
TAZMO INC.
- Vietnam**
TAZMO VIETNAM CO.,LTD.
FACILITY HANOI CO.,LTD.

- 1972** ● - TAZMO Co., Ltd. is incorporated to manufacture and produce electronic components and repair industrial equipment.
- 1980** ● - Began production of molding dies, including injection molding dies.
 - Completed development of Fully-automated Photo Resist Coater; production and sales started.
- 1989** ● - Developed TFT Full-color filter manufacturing system; production and sales started.
- 1990** ● - Constructed new head office/plant at 6186 Kinoko-Cho, Ibara, Okayama
 - Developed and produced Ultra Compact Transfer System for Super Clean Room.
- 1994** ● - Began production and sales of Emboss Carrier Tape.
- 1995** ● - Began production of injection Molding Products.
- 2001** ● - Developed "CS13" series Photo Resist Coater specialized for a thicker film application; production and sales started.
- 2004** ● - Listed on the JASDAQ market.
- 2008** ● - Established TAZMO VIETNAM CO., LTD. a consolidated subsidiary, in Ho Chi Minh City, Vietnam.
- 2009** ● - Developed 10th generation compatible full-color filter manufacturing system; production and sales started.
 - Concluded a license agreement with 3M(USA) for semiconductor manufacturing equipment.
- 2013** ● - Apprecia Technology Inc. became our wholly owned subsidiary company.
 - VIETNAM CO., LTD. Constructed new factory at Long Hau Industrial Park in Long An Province, Vietnam.
- 2017** ● - Facility Co., Ltd. and Quark Technology Co., Ltd. became our wholly owned subsidiary company.
- 2018** ● - Listed on the First Section of the Tokyo Stock Exchange
- 2019** ● - Constructed a new head office at 5311 Haga Kita-ku, Okayama-shi, Okayama
- 2020** ● - Merged with Apprecia Technology Inc.
- 2022** ● - TAZMO's listing transferred to Prime Market in Tokyo Stock Exchange.
 - Increased capital to 3,495,400,000 yen through public offering.
 - Established TAZMO SEMITEC SHAOXING TECHNOLOGY Co., Ltd. a consolidated subsidiary, in Zhejiang Shaoxing, China.

We develop, manufacture, and sell equipment for manufacturing cutting-edge semiconductors and packages, manufacturing equipment for organic EL and liquid crystal displays, and clean transfer robots.

Semiconductor Manufacturing Equipment Business Unit

Using the know-how and technology cultivated over 40 years, we provide equipment for various processes such as coating, developing, laminating, and peeling in semiconductor manufacturing worldwide.



Transfer Business Unit

Providing various transport systems that are accurate, speedy, and space-saving, including transport robots for silicon wafers, etc., which are essential for semiconductor manufacturing.



Cleaner Business Unit

Providing silicon wafer cleaning and slurry supply equipment, which is an important process in semiconductor manufacturing, as well as equipment that regenerates and reuses phosphoric acid from waste liquid.



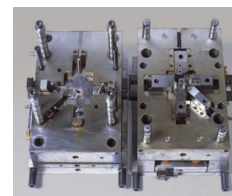
Coater Business Unit

Providing various flat panel manufacturing equipment such as liquid crystal displays. We are currently developing PLP equipment and nanoimprint equipment.



Molding Business

Mold technology, which is essential for parts manufacturing, has been a core technology since our founding, and we provide a variety of products to meet the various needs of user companies.



Surface Treatment Business

Providing plating processing equipment for printed circuit boards incorporated in semiconductor packages and electronic control systems for automobiles, etc.

